

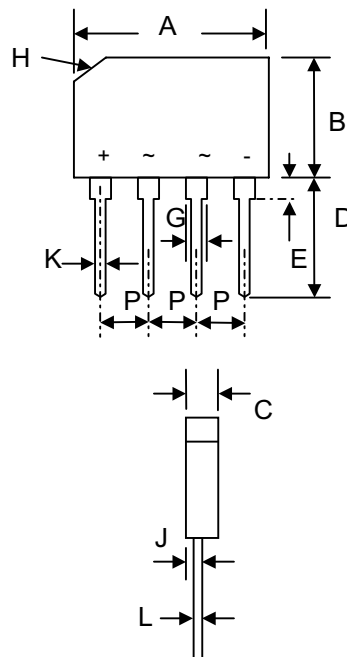
Data Sheet 1332 Rev.—

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 2.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



GBP		
Dim	Min	Max
A	14.25	14.75
B	10.2	10.6
C	3.8	4.7
D	14.25	14.73
E	2.29	—
G	1.17	1.42
H	2.8 x 45°	
J	1.14	1.52
K	0.76	0.86
L	0.3	0.64
P	3.56	4.06
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBP 2005	GBP 201	GBP 202	GBP 204	GBP 206	GBP 208	GBP 210	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @T _A = 50°C	I _O	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50							A
Forward Voltage (per bridge) @I _F = 2.0A	V _{FM}	1.1							V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _R	10 1.0							μA mA
Operating Temperature Range	T _j	-55 to +125							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

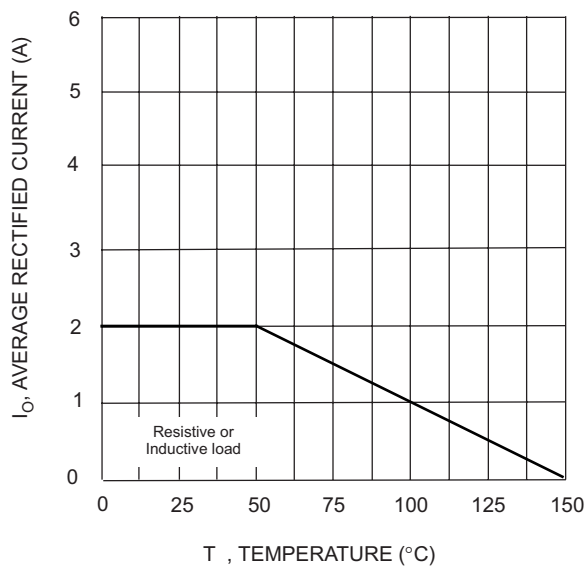


Fig. 1 Forward Current Derating Curve

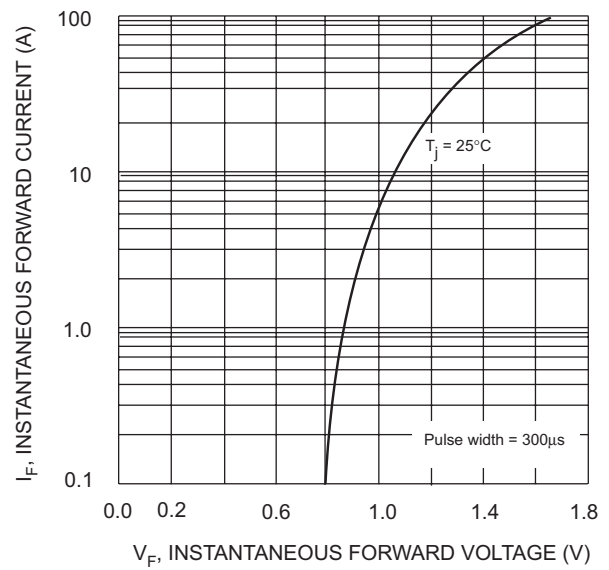


Fig. 2 Typical Fwd Characteristics, per element

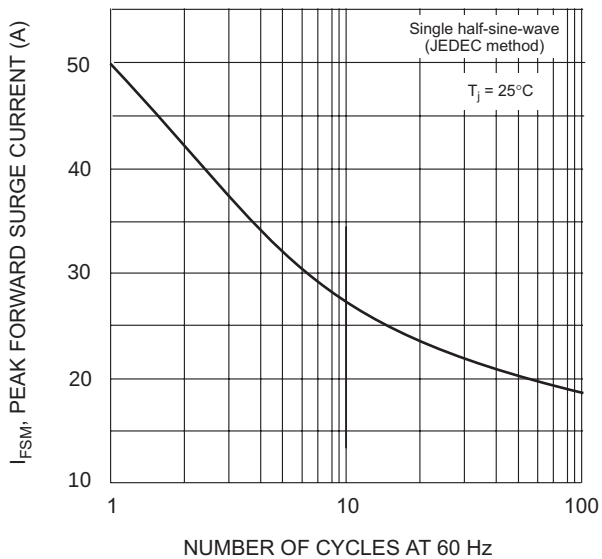


Fig. 3 Maximum Non-Repetitive Surge Current

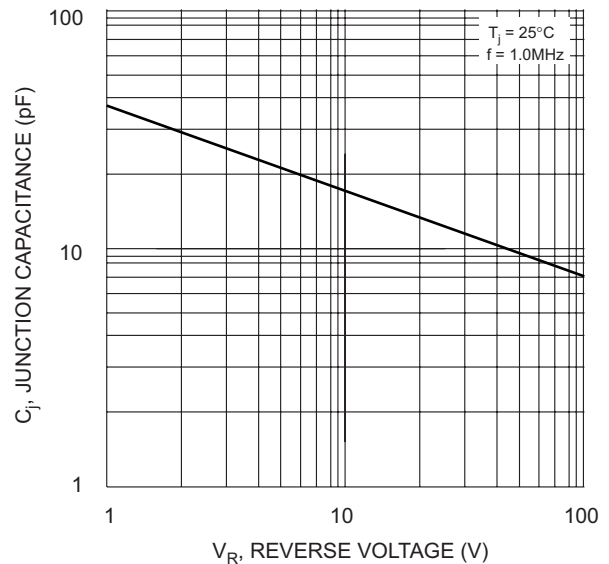


Fig. 4 Typical Junction Capacitance

TECHNICAL DATA

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